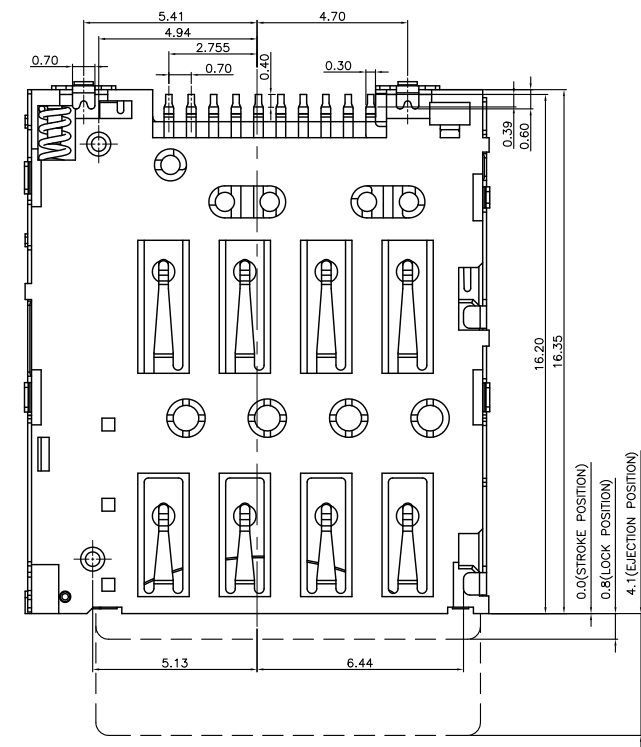
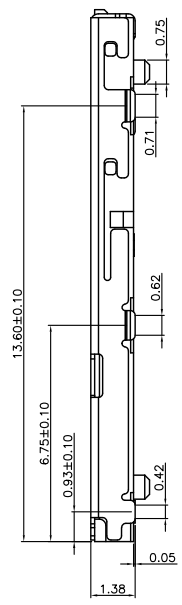
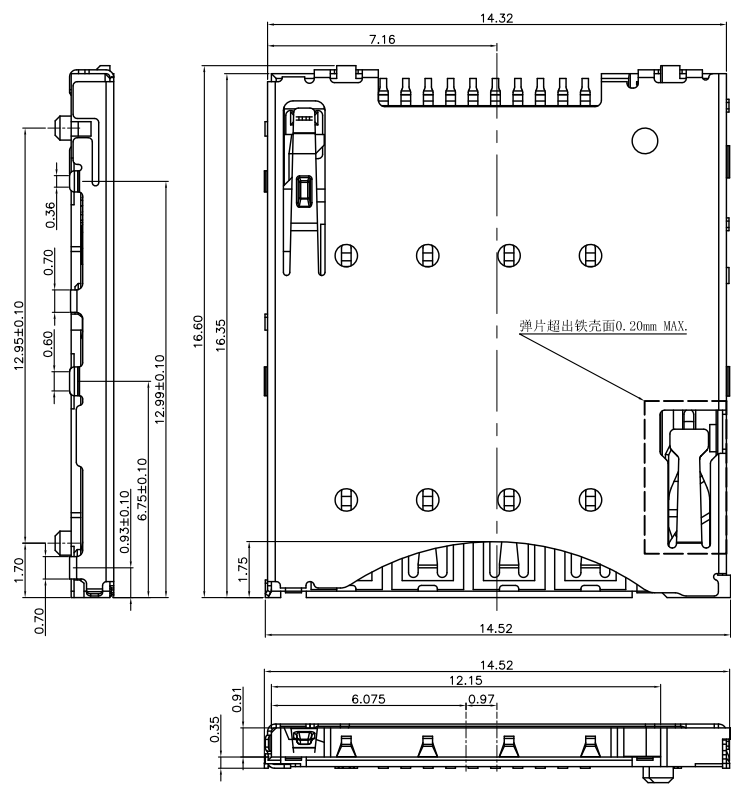


更改 REV	修改 MODIFICATION
A	ECXXXX



NOTES :

1. MATERIAL :

- 1.1 HOUSING/SLIDER:LCP UL94 V-0, BLACK COLOR.
- 1.2 SHELL: SUS304-H T=0.12mm
- 1.3 CONTACT: C5210-EH T=0.12mm

2. FINISH :

- 2.1 CONTACT: Au 1-3u" ON CONTACT AREA,  
Au 1u"MIN ON SOLDER TAIL AREA.
- 2.2 SHELL: 50u" MIN NICKEL PLATING OVERALL.  
Au 1u"MIN ON SOLDER TAIL AREA.

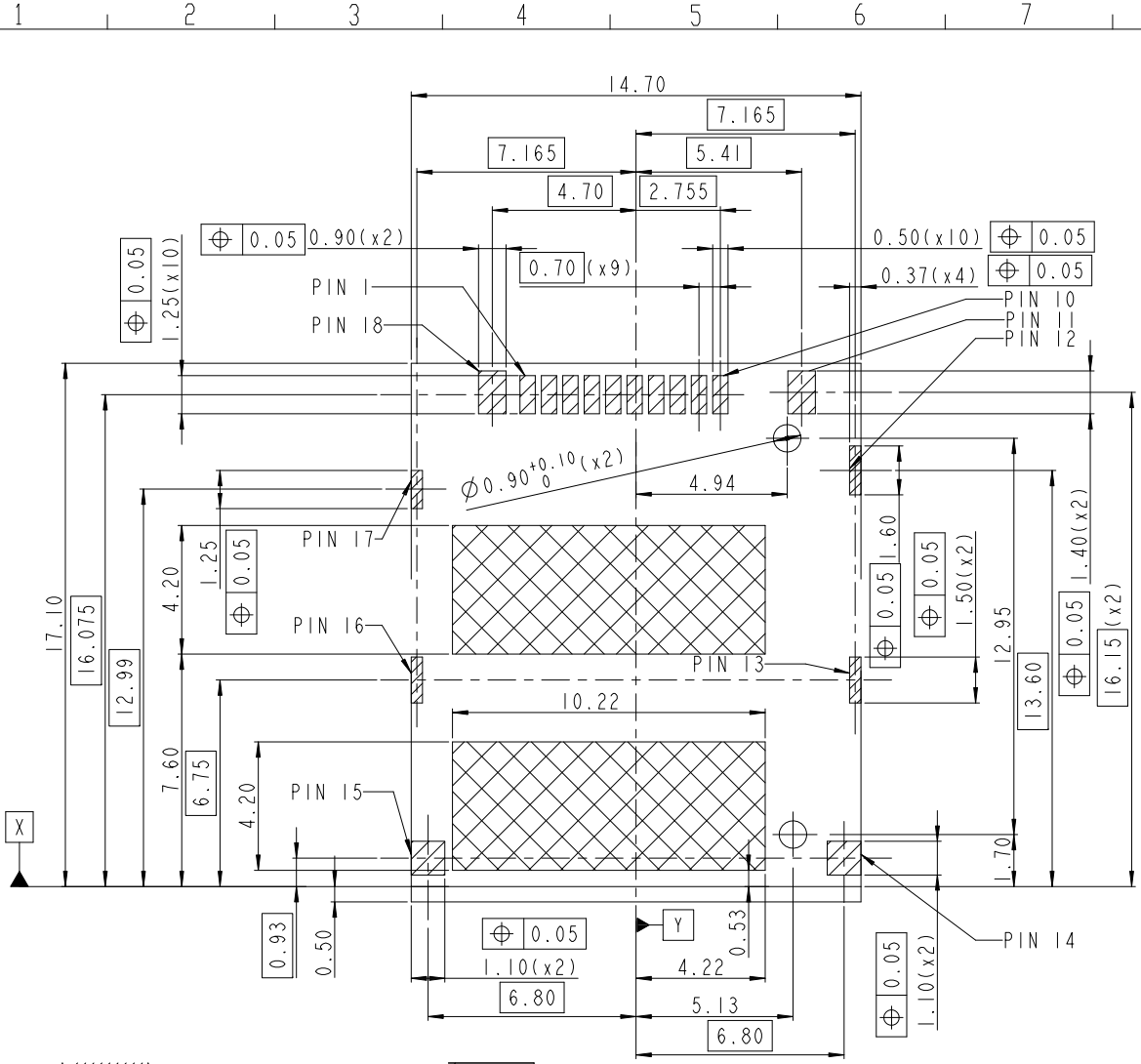
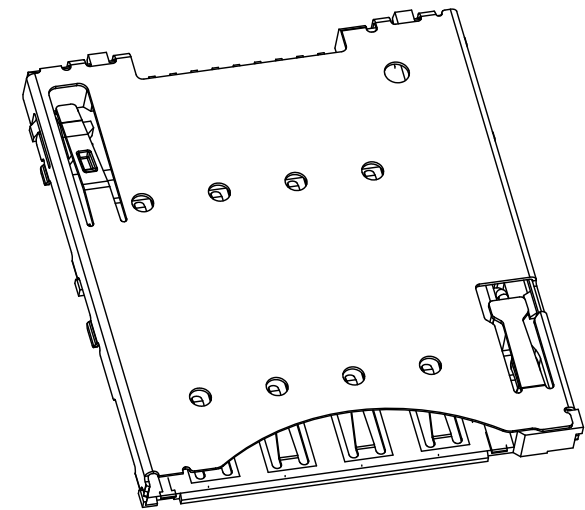
3. ELECTRICAL CHARACTERISTICS:

- 3.1 OPERATING TEMPERATURE: -25°C~+85°C.
- 3.2 CONTACT RESISTANCE: Contact Pin : 150 milliohms MAX.
- 3.3 INSULATION RESISTANCE: 500 M OHMS Min. AT 500V DC.
- 3.4 DIELECTRIC WITHSTANDING VOLTAGE: 0.5mA Max. AT 500VAC.

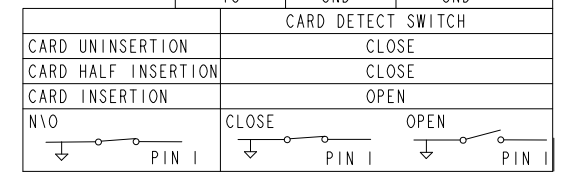


GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 稱(TITLED) MICRO SIM PUSH H1.34	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
單位(UNIT) mm	料 號(PART NO.) 7SIMC-F0-0022	圖 號(DWG NO.) 7SIMC-F0-0022	比例(SCALE) 1:1
審核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	張 數(SHEET) 1 / 2
		更改 REV A	

更改 REV	修改 MODIFICATION
A	ECXXXX



PIN NUMBER	PIN ASSIGN	FUNCTION
1	CD	SIM CARD DETECT
2	C8	RESERVE
3	C4	RESERVE
4	C7	I/O
5	C3	CLK
6	C6	Vpp
7	C2	RST
8	C5	GND
9	C1	Vcc
10	N/A	RESERVE
11	GND	GND
12	GND	GND
13	GND	GND
14	GND	GND
15	GND	GND
16	GND	GND
17	GND	GND
18	GND	GND



- PAD area
- : No component area
- : No trace, no test point, no via hole, no ground area

RECOMMENDED PCB LAYOUT  
TOLERANCE: ±0.05mm

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5°	名称(TITLE) <b>MICRO SIM PUSH H1.34</b>	
X± 0.30	X*± 2°		
.XX± 0.20	.XX*± 1°	图号(DWG NO.) 7SIMC-F0-0022	
单位(UNIT) mm	料号(PART NO.) 7SIMC-F0-0022	图号(DWG NO.) 7SIMC-F0-0022	
审核(APPROVAL)	核准(CHECKED)	製圖(DRAWN)	比例(SCALE) 1:1
			张数(SHEET) 2 / 2
			更改(REV) A

